nanoveu

An applied technology company

PITT STREET RESEARCH

Semiconductor Conference 2025 Presentation

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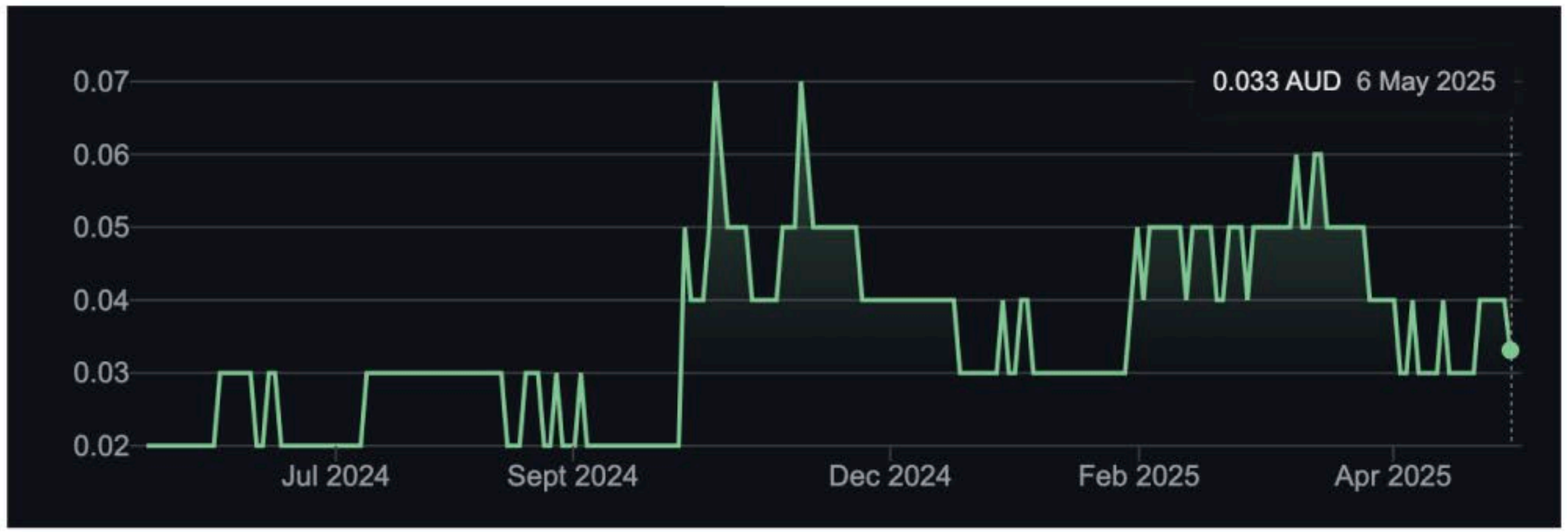
Capital Structure

Nanoveu Share Price

ASX – Delayed Quote – AUD
Nanoveu Limited (NVU.AX)
1D 5D 1M 6M YTD 1Y 5Y All

$0.033



Capital Structure*

ASX Code	NVU
Shares on Issue	742.4m
Options on Issue	235.3m
Performance Rights on Issue	157.1m
Previous Close	$0.035
Average Volume	2.42m
Market Cap	$25.98m

*Before issuance of securities from placement on 01/05/25

Our Board

DR. DAVID PEVCIC
Executive Chairman

- Experienced professional and investor in the resources and technology sector.
- Non-Executive Chairman at Battery Age Minerals Ltd (ASX: BM8).
- Non-Executive Director at Infini Resources Ltd (ASX: I88).
- Holds a Bsc, MBBS, from the university of Western Australia.

ALFRED CHONG
Group Chief Executive Officer

- Founder Of Nanoveu, Has 30+ Years Of Experience In Scaling Companies And Trade Sales.
- Former CEO Of: Atex Media Command (APAC) ,THISS Technologies, 121View.
- Former CMO At 3D International.

STEVE APEDAILE
Non-Executive Director

- 30 Years Of Experience In Accounting.
- Worked At KPMG And Horwath Hong Kong.
- Fellow Of The ICAEW.
- Member Of The AICD.
- Executive Chairman Of Sprintex (ASX:SIX).

DR. MICHAEL WINLO
Non-Executive Director

- Former CEO Of Linear Clinical Research.
- Former Health Lead At Palantir (NYSE:PLTR).
- Holds An MBA From Stanford And An MBBS From UWA.

Semiconductor Leadership Team

“We are positioning ourselves to ourselves to meet growing global global demand for low energy but but powerful chips driven by the the increasing demand for AI-supported applications.”

Mark Goranson
CEO of Semiconductor Technology

Notable Positions

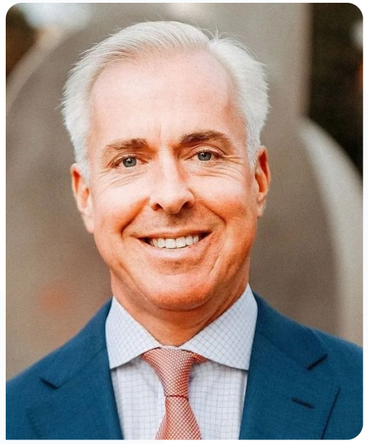
- Vice President of global operations, TE connectivity (NYSE: TEL).
- Senior Vice President of Fab Operations, ON Semiconductor (NASDAQ: (NASDAQ: ON).
- Vice President of Fab Operations Freescale Semiconductor (NYSE: FSL). (NYSE: FSL).
- Early member of Intel Corporation (NASDAQ: INTC) for 18-years.
- Holds a B.Sc. in Physics/Electronics from New Mexico Tech.

"EMASS’s ultra-low-power semiconductor technology has has remarkable potential to transform AI enabled hardware, hardware, addressing a critical industry need for more efficient efficient edge computing."

Dr. Mohamed M. Aly
Founder of EMASS

Notable Positions

- Associate Professor at NTU Singapore, specializing in AI computing computing systems.
- Former Postdoc at Stanford (2014–2017).
- Senior IEEE Member.
- Collaborated with Stanford and TSMC.
- Recipient of the Nanyang Education Award (2023).
- Holds a Ph.D. from EPFL.



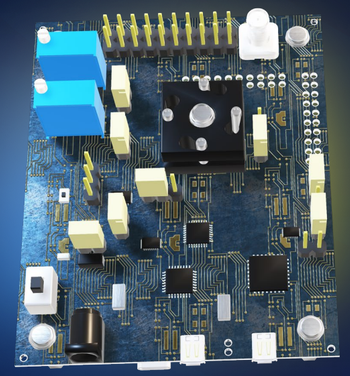
“NVU’s mission to reshape the ultra-low power edge semiconductor landscape through innovation and strategic execution aligns perfectly with my passion”

Scott Smyser
VP, Sales and Marketing, Semiconductor Technology

Notable Positions

- EVP, Worldwide Marketing & Business Development, Si-Ware Systems
- VP & GM, VTI Technologies (Murata)
- SVP of Sales, Atomica
- SVP of Strategic Sales, Rockley Photonics
- Holds an MBA and B.Sc. In Electrical Engineering from University of Southern California

Semiconductor And System On Chip (SoC) For AI Computing “On The Edge”



The Backbone of Modern Tech – Semiconductors & SoCs power healthcare, automotive, and smart IoT, making devices faster & more intelligent.

Compact & Energy-Efficient – Low-power, high-performance AI processing, perfect for next-gen connected technology.

Major Sectors Driving Demand for Energy Efficient AI Infrastructure

Aerospace And Defense

- Drones and UAVs for navigation, video processing and communication
- Military radar and surveillance

Consumer Electronics

- Smart Phones and Tablets.
- Wearables and Smartwatches.
- Smart TV and appliances.

Smart Cities

- Robotics and real time control.
- Predictive maintenance to collect and process sensor data on equipment health.

Healthcare

- Portable diagnostics equipment's
- Imaging Systems like CT and MRI use SoCs for advanced processing

Automotive

- Optimized Battery Management.
- Seamless Navigation Systems.
- Enable Safe And Intelligent Driving.

Energy And Utilities

- Smart Meters for efficient energy resource management
- Optimized solar and wind energy systems

Gaming & Entertainment

- Used in consoles for graphics and processing.
- VR/AR for immersive experiences.

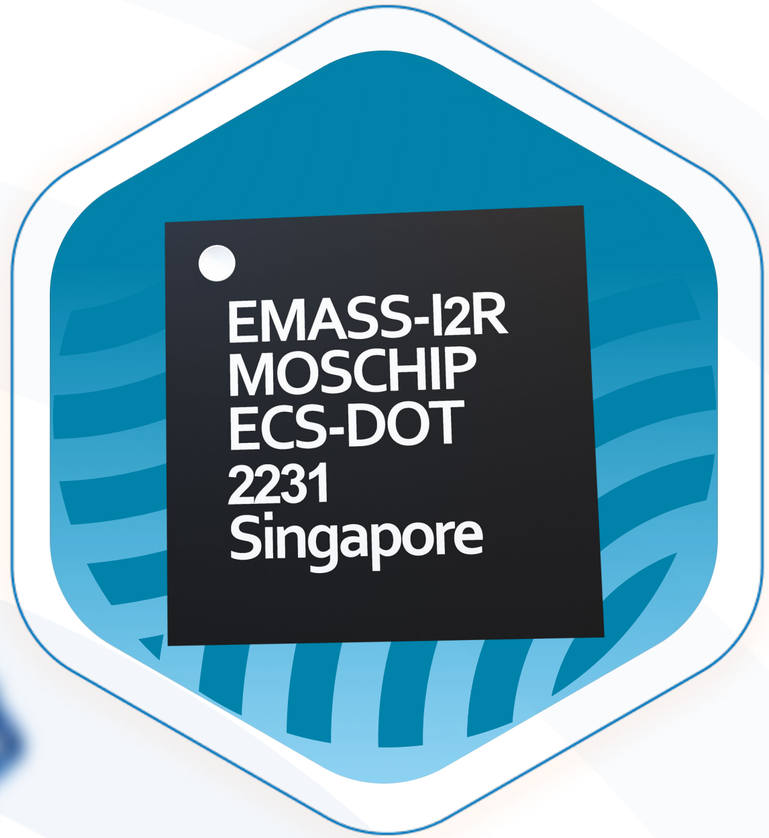
Data Centers & Cloud Computing

- Unprecedented growth in demand for cloud computing to support AI and ML usage

Telecommunications

- Networking communications such as Routers and Modems.
- Satellites for space communication.

The EMASS Opportunity



1 An SoC With AI Capabilities

- **Problem** – Increasing demand for computational power that can handle AI workloads on the "edge", faster data processing and analysis
- **Solution** – EMASS's chip is capable of high AI workloads at its low power and form factor

2 Ultra Energy Efficient

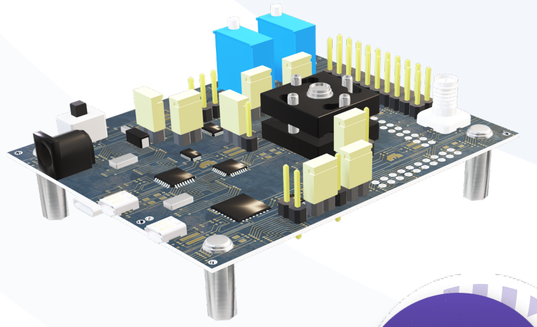
- **Problem** – Current Solutions struggle to run AI computations without high power consumption
- **Solution** – EMASS can run AI models efficiently allowing for a wide range of applications

3 High Levels Of Interoperability

- **Problem** – Integrating SoCs into edge devices can be complex
- **Solution** – EMASS's RISC–V architecture is widely accepted with a strong community ensuring seamless integration, and future–proof solutions .

Superior Performance, Low Power, Small Form Factor

Leveraging The RISC-V Chip Architecture For Efficiency And Interoperability



Integrated EMASS SoC with AI & Accelerator module

AI Capacity

30 Giga-Operations Per second @ 50 MHz, 2mW

Power Efficiency

Up to 12 TOPs/Watt

On-chip dense memory

4 MBytes

Hardware support for compressed AI models

Compressed AI Model < 2-bits

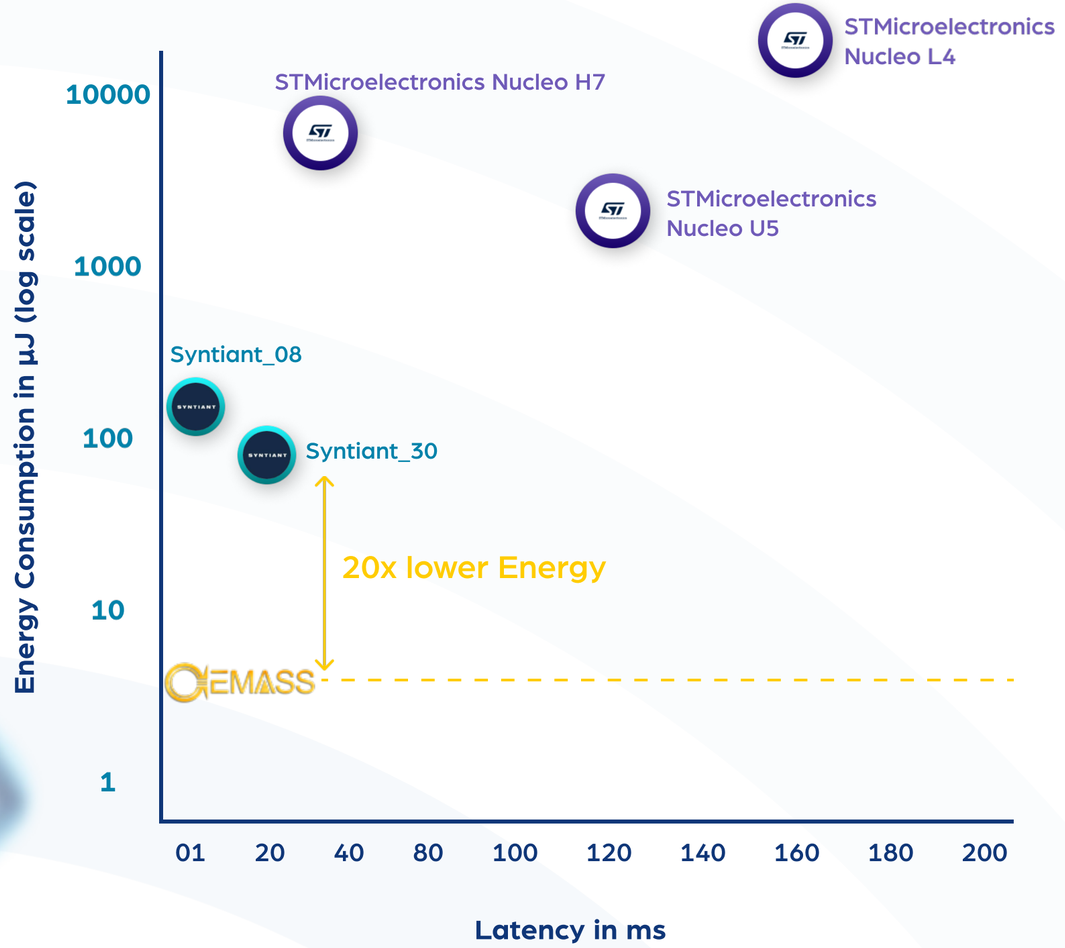
Physical size

22nm technology with 7mm^2 die area

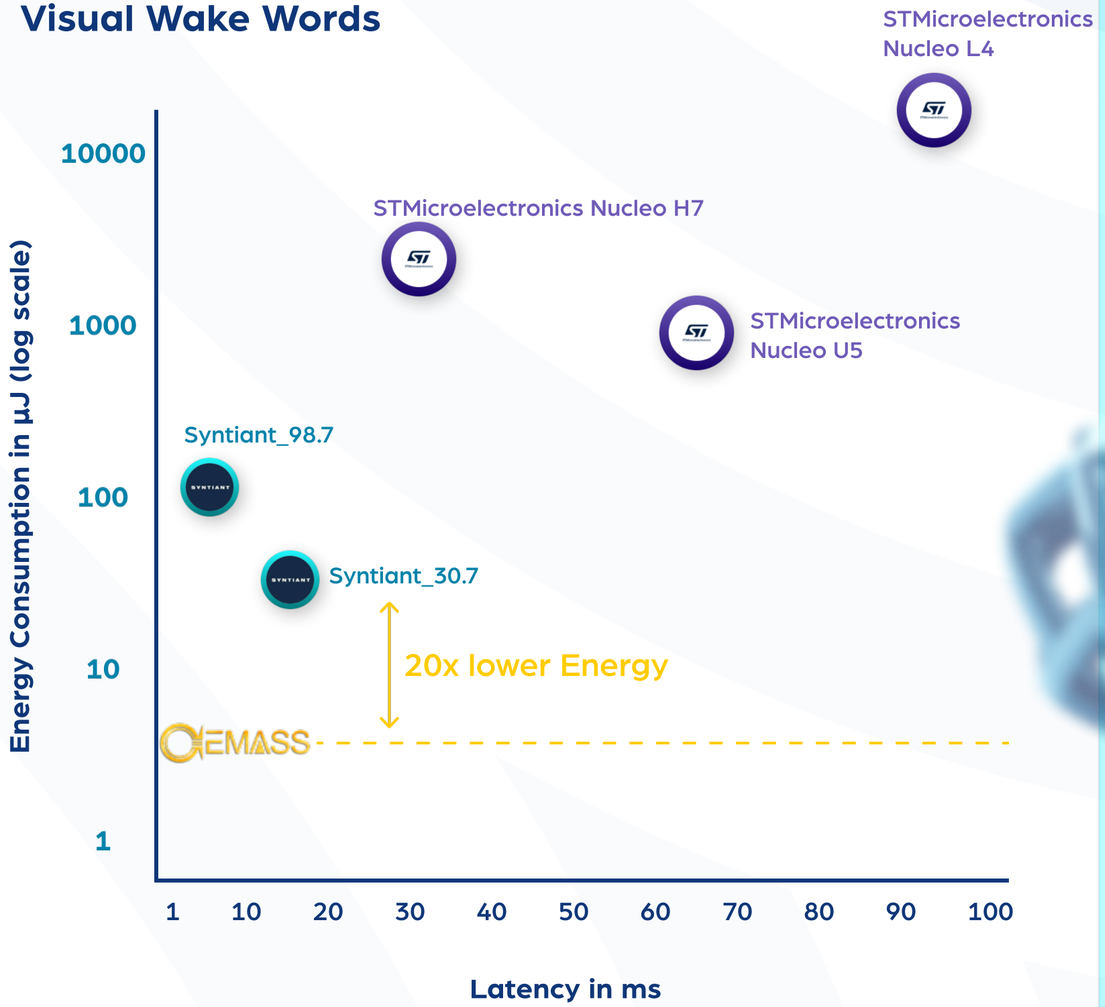
EMASS Exceptional AI Computation, 20X Lower Energy

EMASS's SOC has greater AI performance compared to today's leading chips

Image Classification



Visual Wake Words



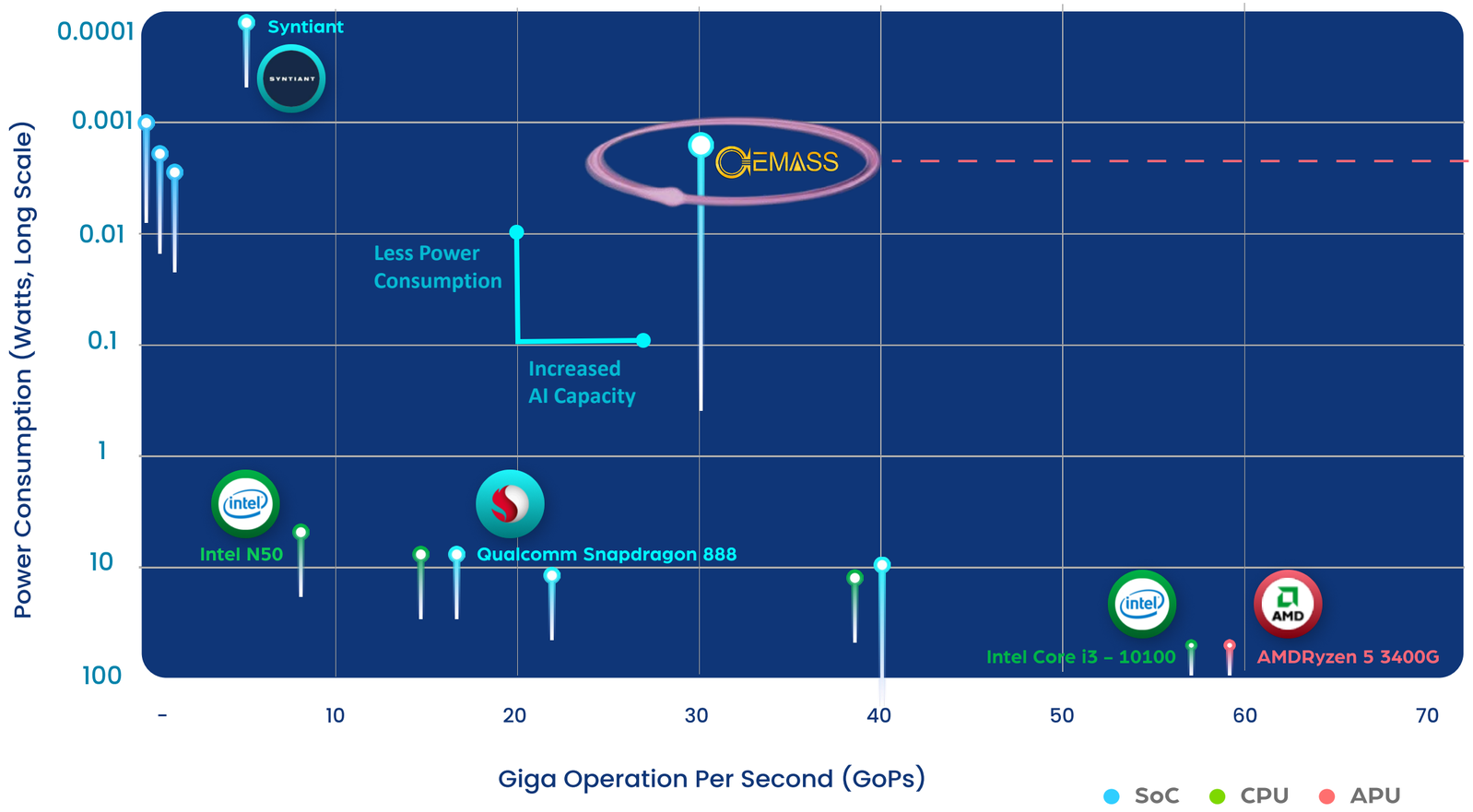
EMASS Leads Industry Peers In AI Computation Tasks

Company	Software Optimization	Target Application	AI Performance per Watt (Avg/Peak)	Power (Avg/Peak)	AI Performance	Max AI Parameters
Nanoveu	YES	3D Vision, Health Monitoring, Wearable, Smart infrastructure	3/15 ToPs	0.1mW/10mW	30 GOPs	13 million
Maxim Integrated	NO	Medical, Patches, Wearable	1.6/64 GoPs	50mW/2W	3.2 GOPs	3.5 million
Himax	NO	Vision, Speech, Gesture, Agriculture, Retail	40/320 GoPs	2.5mW/20mW	0.8 GOPs	500 K
Syntiant	NO	Vision, Smart home, Smartwatches	0.1/1 ToPs	7/30mW	6.4 GOPs	7 Million
Ambiq	NO	Smart home, Smart watches, Fitness trackers, Animal tracker, Voice remote	240/133 GoPs	1mW/1.8mW	0.24 GOPs	1 Million
ETA Compute	NO	Vision	200 GoPs	2mW	0.4 GOPs	256 K

*GoPs ≈ Clock Speed (GHz) × Instructions Per Cycle (IPC) × Number Of Cores

EMASS Delivers Exceptional Energy Efficiency

EMASS's SOC has greater AI performance compared to today's leading chips



EMASS SoC: Power-Efficient AI For Next-Gen IoT

- Complete AI Capability – EMASS SoC delivers full AI operations with top power efficiency.
- Optimized for IoT – Ideal for battery-sensitive devices without performance loss or extra power drain.
- Seamless Integration – No hardware modifications required, enabling next-gen IoT development.

EMASS Has Leading Energy Efficiency Compared To Peers

EMASS nanoveu

Selected Chip Performances

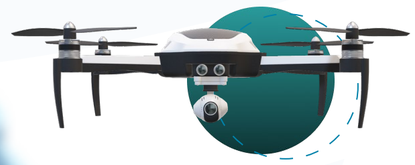
Company	Chip	Chip Type	Target Industry	Max Performance per Watt	Power Consumption(TBP)	Max Perfomance
NANOVEU	EMASS	SOC	IoT, Wearables, Drones Artificial Intelligence	3–15 TOPS	0.1 – 10 MilliWatts	~30 GoPs
AMD	Ryzen 5 3400G	APU	Computing	~0.91 TOPS	65 Watts	~59 ToPs
INTEL	Processor N50	CPU	IoT, Chromebook	~0.53 TOPS	75 Watts	~40 ToPs
ARM	Cortex–A53	CPU	Smartphone, Tablets, Wearables, IoT	~0.0019 TOPS	7.5 Watts	~14 GoPs
QUALCOMM	Snapdragon 888	SOC	Artificial Intelligence, Wearables, Smartphone	~2.1 TOPS	8 Watts	~17 ToPs
BROADCOM	BCM2712	CPU	Robotics, industrial automation, edge computing	~3.2 TOPS	12 Watts	~38 ToPs
MEDIATECH	Helio P60	SOC	Artificial Intelligence Processing, Smartphones	~4 TOPS	10 Watts	~40 ToPs
MARVELL	Octeon TX2	SOC	5G Networks & Data Centres	~0.67 TOPS	30 Watts	~20 ToPs

*GoPs ≈ Clock Speed (GHz) × Instructions Per Cycle (IPC) × Number Of Cores

EMASS Expands Market Opportunities for Nanoveu

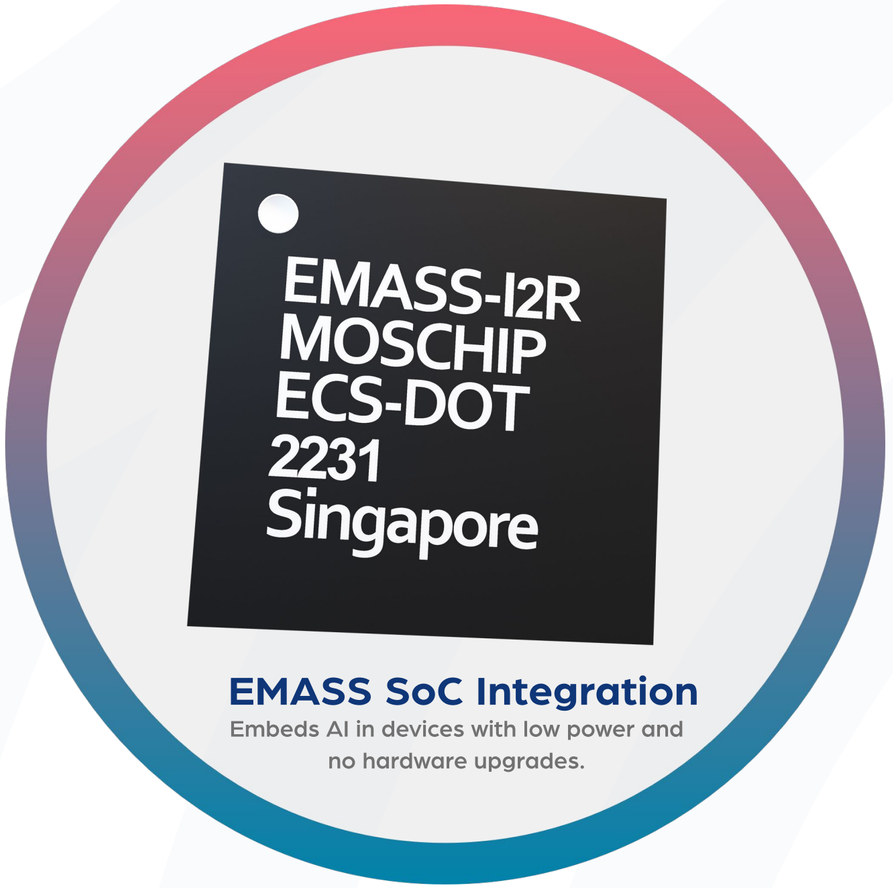
Smartwatch

- Live Biometric Processing – Non-invasive oxygen, hydration, and blood glucose analysis.
- Predictive Diagnosis – Early disease detection.



Drones

- AI Self-Navigating Drones – For crop and livestock monitoring.
- Predictive Harvesting – Using multi-spectral and hyper-spectral data



EMASS SoC Integration

Embeds AI in devices with low power and no hardware upgrades.

Medical Devices

- 2D to 3D Models – Instant scans and integrated medical imaging.
- Real-Time Diagnostics – For pacemakers and cochlear implants.

Glasses & Lens

- 2D to Augmented 3D – Virtual FaceTime and calls.
- Immersive AI Assistant – Enhanced experiences

Advancing Our Semiconductor Roadmap

Strengthening our position as the leader in ultra-low-power, high-efficiency Edge AI through next-generation IP development

Strategic Collaboration

nanoveu x Center of Nanoelectronics & Devices (CND)

Strategic Advisor Appointed
Dr. Yehia Ismail (Director, CND) joins as Strategic Advisor to Nanoveu

Partnership with CND (Cairo)
Advanced SoC design and nanoelectronics expertise

Collaborative R&D
Joint development of next-gen edge AI chips on TSMC 16nm

Strengthening ECS-DoT Platform
Co-developing IP to accelerate innovation and independence

Defined Technical Goals

Cutting-Edge 16nm FinFET Node
Utilising TSMC's advanced 16nm FinFET process for ultra-efficient AI chips

Performance-Per-Watt Optimization
Increase energy efficiency and thermal stability

Advanced On-Chip Compression
Expand model size with ~1.3bits/weight architecture

Scalable Integration Across Devices
Diverse use cases with more advanced AI

Business Impact & Scalability

Strengthening Market Position
Enhanced competitiveness in edge AI hardware.

Global Scale & Export Readiness
Chips tailored for fast-growing international markets.

Bolstering of IP Portfolio
Expanding proprietary technology to strengthen our competitive moat.

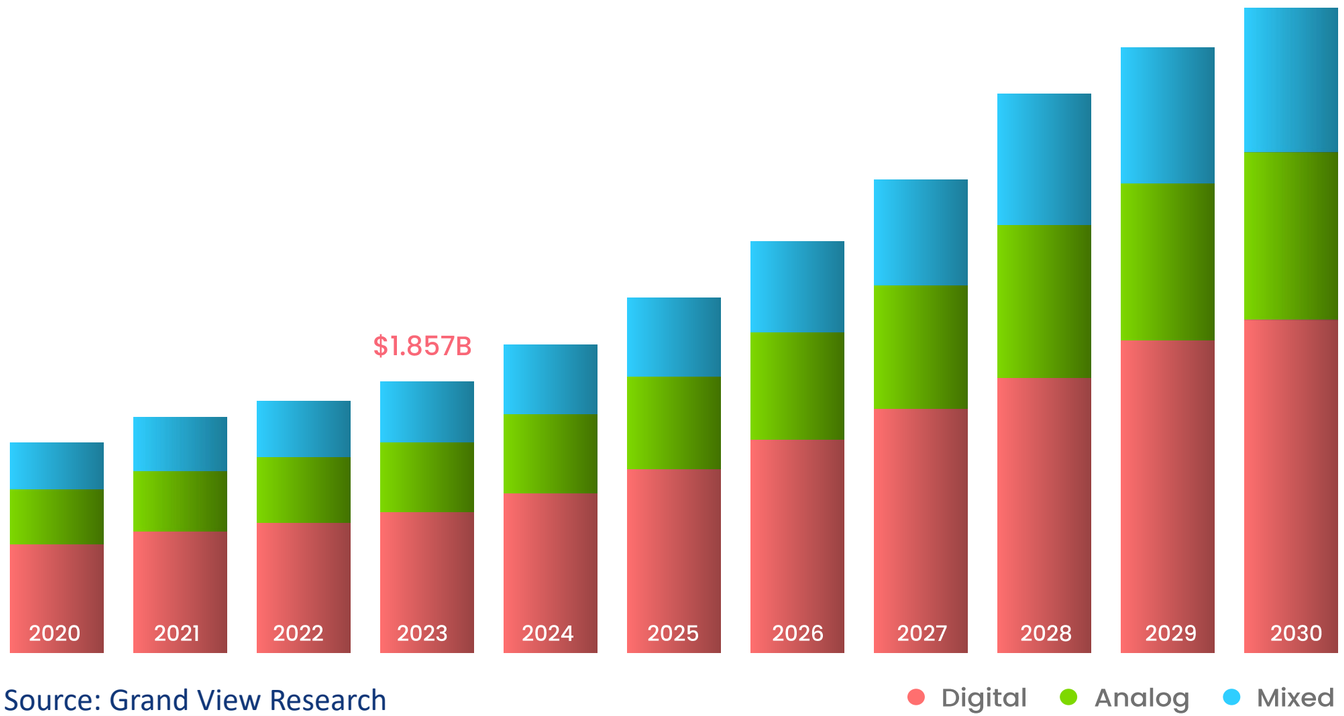
Access to Talent & Regional Innovation
Egypt as a launchpad for deeper MENA engagement.

Semiconductor & SoC Market Set For Rapid Growth

Powering The Future Of AI & Devices

System On Chip Market Size

By Type 2020–2030 (USD Billion)



Source: Grand View Research

SOC Powering The Future Of AI & Devices:

Essential for Next-Gen Tech – SoCs power AI, IoT, and autonomous systems with compact, high-performance computing.

Set to hit

$325.7B by 2030

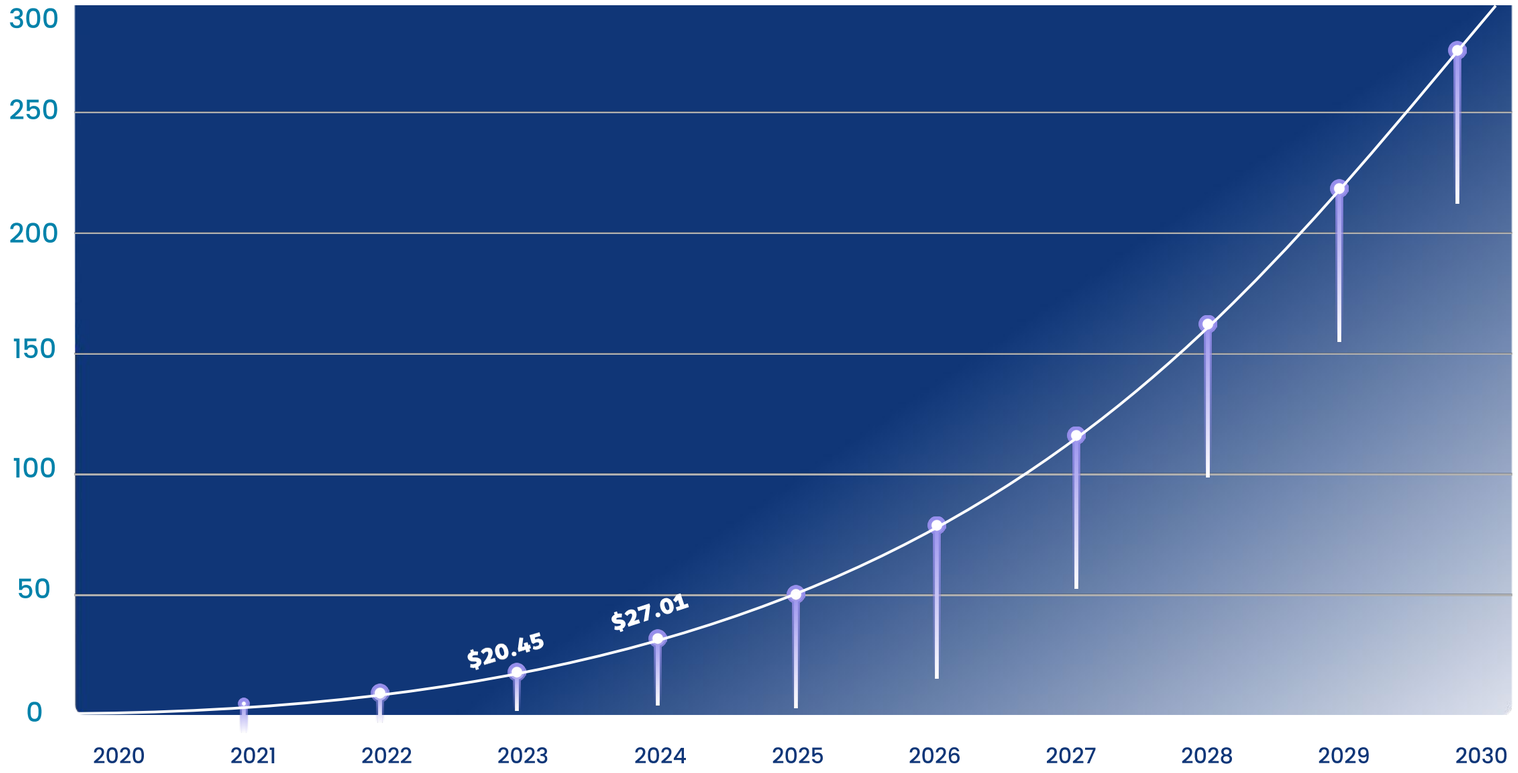
8.5% Global Market CAGR

Driven by AI, 5G, and smart devices.

Poised For Exponential Growth

Edge AI Smart And Efficient Computing For IOT

Edge AI Growth Rate



Source: Fortune Business Insights

Edge AI: Smart & Efficient Computing For IoT

Faster, Smarter AI – Powers real-time decisions for IoT, autonomous vehicles, and next-gen tech.

Expected To Reach

$269.82B by 2030

33.3% CAGR

As AI moves to on-device processing.

Global Development and Collaboration Partners

EMASS has been developed with the world's leading Chip manufacturers and partners

NTUitive Pte Ltd

NANYANG TECHNOLOGICAL UNIVERSITY SINGAPORE

Agency for Science, Technology and Research SINGAPORE

Early Backers, IP & Development

Weebitnano THE NEXT NVM IS HERE

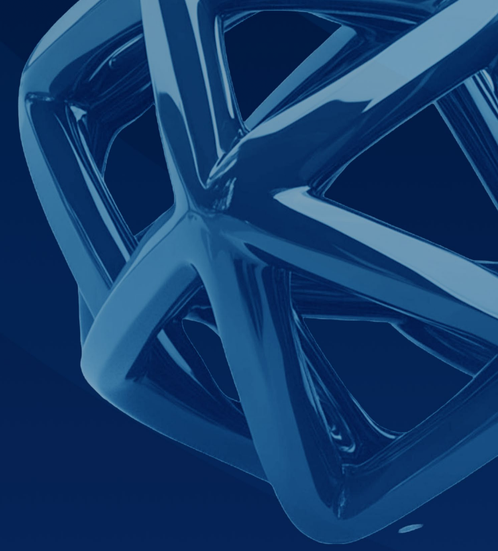
ReRAM Collaboration Partner

tsmc

MOSCHIP

IC Fabrication, PCB Fabrication, Packaging

nanoveu



Thank You

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